

Listing of Claims:

1-56. (Cancelled)

57. (Previously presented) A light emitting device comprising:

- a first mirror;
- a light emitting active layer disposed above said first mirror;
- at least a first oxidizable layer having an oxidized region which is significantly oxidized, said first oxidizable layer being disposed above said light emitting active layer;
- at least one semiconductor layer residing above at least a portion of said first oxidizable layer;
- a second mirror disposed above said light emitting active layer;
- top and bottom electrical contacts disposed to communicate with said light emitting active layer; and
- interconnect metallization deposited above at least a portion of said semiconductor layer and in contact with said top electrical contact.

58. (Previously presented) The laser recited in claim 57, wherein said first oxidizable layer further comprises a second region which is not significantly oxidized.

59. (Previously presented) The laser recited in claim 57, further comprising at least one basin disposed proximal to said oxidized region.

60. (Previously presented) The laser recited in claim 59, wherein said basin is provided for allowing said first region to be oxidized.

61. (Previously presented) The laser recited in claim 57, wherein said top contact is characterized by a center.

62. (Previously presented) The laser recited in claim 61, further comprising at least one pit disposed proximal to said oxidized region, said pit not hemming said center.

63. (Previously presented) The laser recited in claim 62, wherein said pit is provided for allowing said first region to be oxidized.

64. (Previously presented) The laser recited in claim 57, wherein said semiconductor layer has an electrically insulating region formed by ion implantation.

65. (Previously presented) The laser recited in claim 64, wherein said electrically insulating region resides above at least a portion of said oxidized region.